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CHINA ELECTRONICS CORPORATION HOLDINGS COMPANY LIMITED
中國電子集團控股有限公司*

(Incorporated in the Cayman Islands and continued in Bermuda with limited liability)

(Stock Code: 00085)

**NOTICE OF LISTING ON THE STOCK EXCHANGE OF
HONG KONG LIMITED
CNY2,750,000,000 4.70 PER CENT. BONDS DUE 2017
(Stock Code: 85940)**

Joint Global Coordinators, Joint Bookrunners and Joint Lead Managers

BNP PARIBAS

BOC International

Application has been made to The Stock Exchange of Hong Kong Limited for the listing of and permission to deal in the CNY2,750,000,000 4.70 per cent. bonds due 2017 (the “**Bonds**”) of China Electronics Corporation Holdings Company Limited by way of debt issues to professional investors only as described in the offering circular dated 9 January 2014. The listing of and permission to deal in the Bonds is expected to become effective on or around 17 January 2014.

Hong Kong, 16 January 2014

As at the date of this announcement, the Board comprises one Non-executive Director, namely Mr. Rui Xiaowu (Chairman), three Executive Directors, namely Mr. Xie Qinghua (Managing Director), Mr. Liu Hongzhou (Vice Chairman) and Mr. Liu Jinping, and three Independent Non-executive Directors, namely Mr. Chan Kay Cheung, Mr. Qiu Hongsheng and Mr. Yin Yongli.

* For identification purpose only